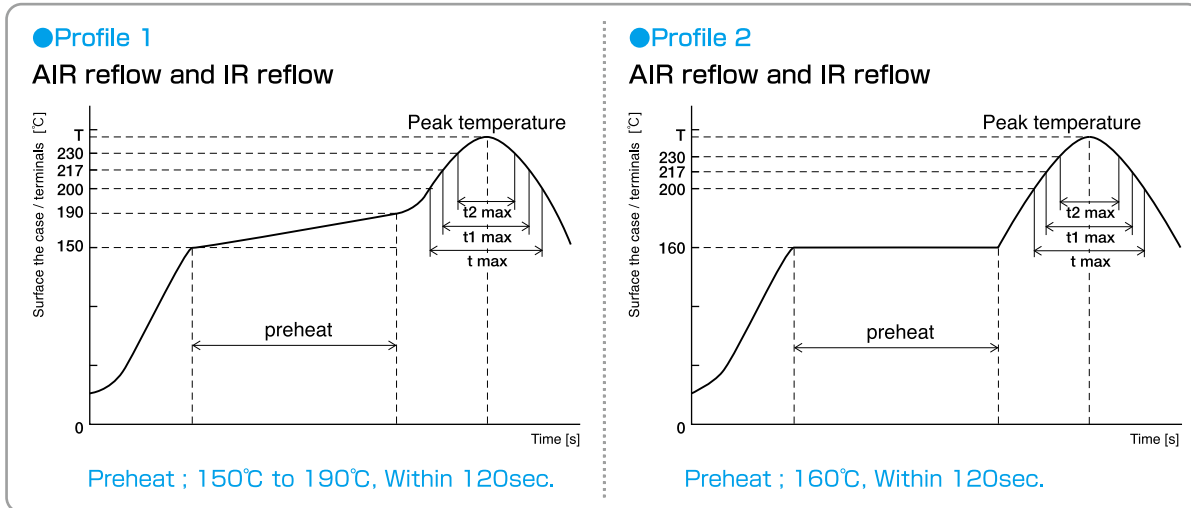


■ Soldering Condition

- Soldering with a soldering iron : within 3 seconds at 350°C unless otherwise specified in the spec.
- Flow soldering : within 10 seconds at 260°C unless otherwise specified in the spec.  
(Do not flow soldering with SMD type.)
- Thermal curing oven : within 2 minutes at below 150°C ambient

■ Reflow Soldering Condition



Series	Voltage (V)	Size	Time of more than 200°C (t)	Time of more than 217°C (t1)	Time of more than 230°C (t2)	Peak temperature (T)	Reflow cycle	Profile
HVA,HVBF	6.3 to 16	ALL	Within 100sec.	Within 80sec.	Within 40sec.	250°C ★1	2	1
HVH,HVP,HVT HVHZ,HVPZ	16 to 63	ALL	Within 100sec.	Within 80sec.	Within 40sec.	260°C ★1	2	1
	80 to 125	ALL	Within 100sec.	Within 80sec.	Within 40sec.	250°C ★1	2	1
HVHF,HVPF	25 to 50	φ6.3	Within 70sec.	Within 40sec.	Within 30sec.	260°C ★2	2	2
		φ8 to φ10	Within 70sec.	Within 40sec.	Within 30sec.	260°C ★2	1	2
	63 to 80	ALL	Within 70sec.	Within 40sec.	Within 30sec.	245°C ★3	2	2

The maximum cycle of reflow soldering is two times. The second cycle must be done after sufficient cooling time for more than one hour to return the temperatures of circuit boards and components back to room temperature.

- ★1 Within 5sec.
- ★2 Less than 260°C
- ★3 Less than 245°C

■ Ripple Current Frequency Coefficient

Series	Capacitance : C (μF)	Frequency : F (Hz)			
		100 ≤ F < 1k	1k ≤ F < 10k	10k ≤ F < 100k	100k ≤ F
HVH, HVP, HVT HVHZ, HVPZ HVHF, HVPF	C ≤ 4.7	0.03	0.30	0.65	1.00
	4.7 < C ≤ 33	0.05	0.32	0.67	1.00
	33 < C	0.10	0.35	0.70	1.00
HVA, HVBF HEA, HEBF	C ≤ 10	0.03	0.20	0.50	1.00
	10 < C	0.05	0.20	0.50	1.00

■ Anti-vibration structure

Available for φ8 and φ10.  
[Type code]

Standard structure	Anti-vibration structure
HV	HA